

Press Release

Nuremberg, August 2018

BMBF Project 'IsoGap' has been launched in the frame of Cluster Internationalization

Under the BMBF funding initiative for the internationalization of excellent clusters, future projects and comparable networks, the Power Electronics Cluster coordinates an international research cooperation between Cluster stakeholders and an industrial consortium around the University of Osaka in Japan. The IsoGap project is about high temperature materials and reliability testing for the new generation of wide bandgap power electronics.

In a two-year conception phase, the Power Electronics Cluster in ECPE e.V. headquartered in Nuremberg, together with selected Cluster stakeholders, has developed an internationalization concept for a research cooperation with Japan. This involves novel wide bandgap power semiconductors (silicon carbide, SiC and gallium nitride, GaN) and their system integration. In the following implementation phase of the cluster internationalization, two BMBF joint research projects, IsoGap and SiC-DCBreaker, were launched on 1 August 2018, with a term of three years and a total funding of three million euros.

In the IsoGap project the cooperation partners on the German side, Conti Temic microelectronic GmbH, Rogers Germany GmbH, Plasma Parylene Systems GmbH, Zestron / Dr. OK. Wack Chemie GmbH, the IALB Institute of the Bremen University, the Fraunhofer Institute IISB and the Power Electronics Cluster in ECPE e.V. work on insulation systems for highly integrated wide bandgap power semiconductor modules as well as on extended reliability tests. The Japanese sub-consortium coordinated by the University of Osaka includes major materials companies for high-temperature assembly and interconnection technologies.

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